



Application Note: JN-AN-1172

JN516x Customer Module Evaluation Tool

This Application Note describes how to use the JN51xx Customer Module Evaluation Tool to place the NXP JN516x microcontroller into a number of test modes that enable measurement of module performance.

Application Overview

The software supplied with this Application Note allows the performance of customer modules based on the NXP JN516x device to be evaluated in various ways including received signal strength, packet error rate (PER), crystal oscillator frequency and current consumption, among others. Some tests require the use of two boards (carrying JN516x-based modules).

The tool is provided in two parts:

- **Customer Module Evaluation Tool:** This is the main part of the tool which provides all functionality except the PER testing (see below)
- **Module PER Test Tool:** This part performs PER testing on a JN516x-based module.

Only one of the above tools can be used at a time. The required application must be loaded into the Flash memory of the module under test.

Compatibility

The software provided with this Application Note is intended to be used with the following kits and SDK (Software Developer's Kit) versions:

Product Type	Part Number	Version	IC
Evaluation Kit JN5168	JN516x-EK001	-	JN5161/64/68
Evaluation Kit JN5169	JN516x-EK004	-	JN5169
SDK Libraries	JN-SW-4163	1416	JN516x
BeyondStudio for NXP	JN-SW-4141	1308	JN516x

Building and Downloading the Application

The JN51xx Customer Module Evaluation Tool is provided in this Application Note as two applications: **AN1172_CustomerModuleEvalTool** and **AN1172_ModulePerTest**.

These applications can be built for the JN5169, JN5168, JN5164 and JN5161 microcontrollers using the BeyondStudio for NXP or makefiles.

In order to build the supplied software, the application's folder must be placed in the **workspace** folder of the BeyondStudio for NXP installation:

<BeyondStudio for NXP Installation root>\workspace

where **<BeyondStudio for NXP Installation root>** is the path into which BeyondStudio for NXP was installed (by default, this is **C:\NXP\bstudio_nxp**). The **workspace** directory is automatically created when you start BeyondStudio for NXP.

Build the application as described in the appropriate section below, depending on whether you intend to use BeyondStudio for NXP or makefiles.

Using BeyondStudio for NXP

To build one of the applications and load it into a JN516x-based module, follow the instructions below (only one application can be present in Flash memory at a time):

1. Ensure that the project directory is located in
<BeyondStudio for NXP Installation root>\workspace
2. Start BeyondStudio for NXP and import the relevant project as follows:
 - a) In BeyondStudio, follow the menu path **File>Import** to display the **Import** dialogue box.
 - b) In the dialogue box, expand **General**, select **Existing Projects into Workspace** and click **Next**.
 - c) Enable **Select root directory** and browse to the **workspace** directory.
 - d) In the **Projects** box, select the project to be imported and click **Finish**.




Note:

For **JN5169** device, specify `JENNIC_CHIP=JN5169`

For **JN5168** device, specify `JENNIC_CHIP=JN5168`

For **JN5164** device, specify `JENNIC_CHIP=JN5164`

For **JN5161** device, specify `JENNIC_CHIP=JN5161`

3. Build the application. To do this, ensure that the project is highlighted in the left panel of BeyondStudio and use the drop-down list associated with the hammer icon  in the toolbar to select the relevant build configuration – once selected, the application will automatically build.

The binary file will be created in the **Build** directory, the resulting filename indicating the chip type (e.g. **JN5169**) for which the application was built.

4. Load the resulting binary files into the board. You can do this using the integrated Flash programmer, as described in the *BeyondStudio for NXP Installation and User Guide (JN-UG-3098)*.

Using Makefiles

The **Build** directory contains the makefiles for the applications. A makefile covers both applications.

To build the applications and load one of them into a JN516x-based module, follow the instructions below (only one application can be present in Flash memory at a time):

1. Ensure that the project directory is located in

<BeyondStudio for NXP Installation root>\workspace

2. Start an MSYS shell by following the Windows Start menu path:
All Programs > NXP > MSYS Shell
3. Navigate to the **Build** directory for the applications and then enter a make command, as described below.

The instruction below assumes that the type of JN516x chip has been specified in the makefile (e.g. `JENNIC_CHIP=JN5168`).

At the command prompt, enter:

```
make clean all
```

Alternatively, the JN516x chip type can be specified in the make command – for example:

```
make JENNIC_CHIP=JN5168 clean all
```

4. Load one of the resulting binary files into the board. You can do this from the command line using the JN51xx Production Flash Programmer (described in the *JN51xx Production Flash Programmer User Guide (JN-UG-3099)*).

Setting Up and Running the Tool

You will access the tool running on the JN516x-based module from a PC. Set up a connection between a PC and the board (carrying the JN516x-based module) as follows:

1. If not already done, load the desired application into a JN516x-based module. The possible applications are:

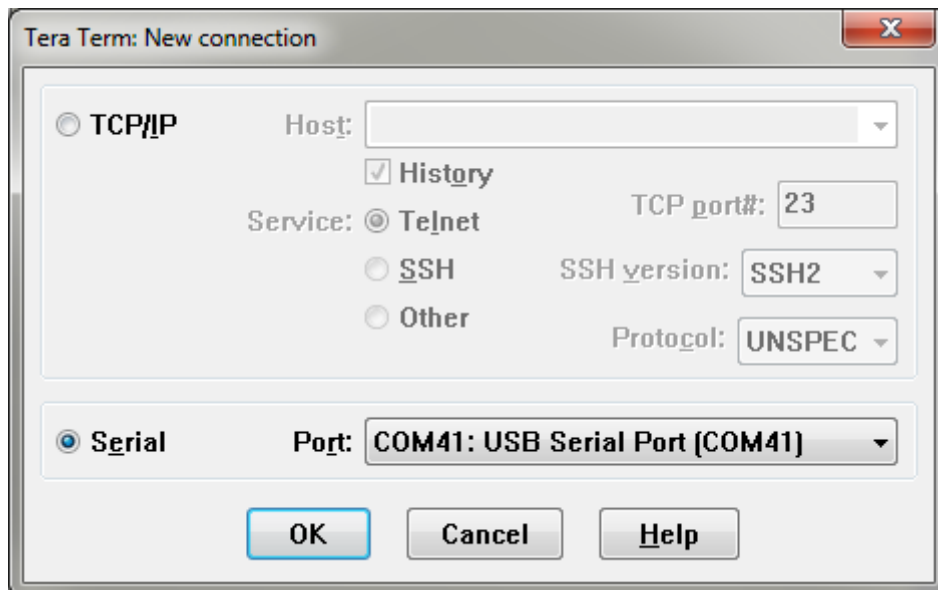
- **AN1172_CustomerModuleEvalTool_JN51xx.bin**
- **AN1172_ModulePerTest_JN51xx.bin**

This step involves connecting a PC to the Carrier Board using a 'USB A to Mini B' cable (supplied in JN516x-EK001). Once application loading has completed, leave this cable connected.

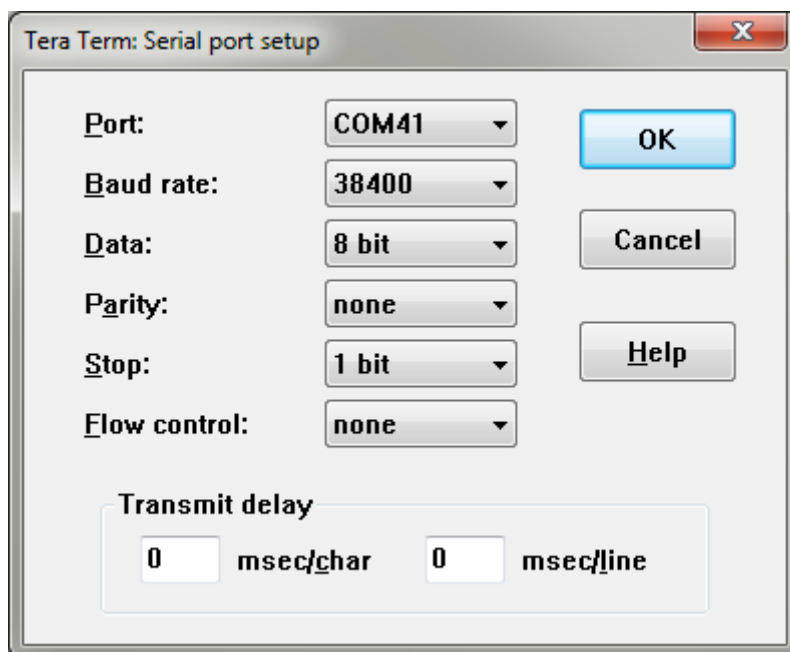
2. Reset the target board.
3. Open a connection to the board using a terminal emulator at 38400 baud, no parity, 8 data bits, 1 stop bit and no handshaking.

Operational instructions are provided below for those using Tera Term to interface with the tool.

1. Launch Tera Term: **All Programs > Tera Term > Tera Term.**
2. Select the **Serial** radio button, then choose the serial communications port that the board is connected to and then click **OK**

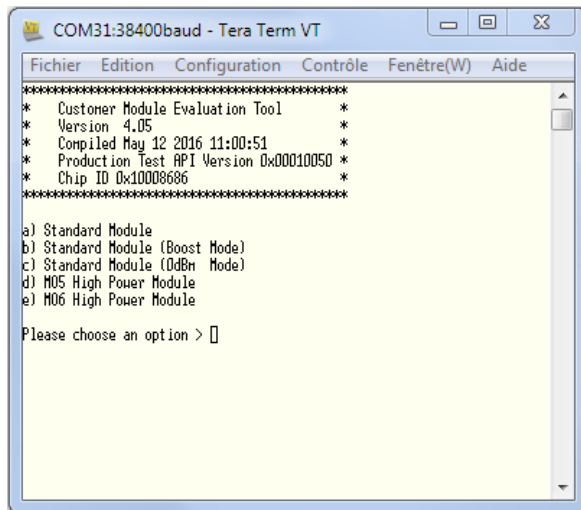


3. Open the **Serial port setup** dialogue box, via the **Setup > Serial Port** menu path. Set the port settings to 38400 bits per second, 8 data bits, no parity, 1 stop bit and no flow control, then click **OK**.

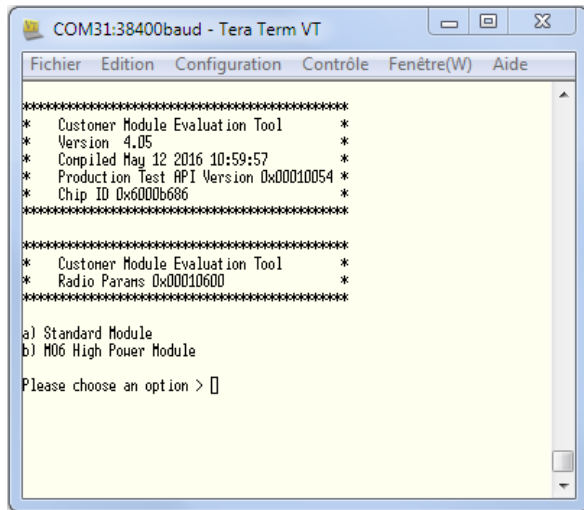


4. Press any key, and the relevant screen from those shown below will be generated by the board.

JN5161/64/68:



JN5169:



5. In the above screen:
 - a) Select the appropriate module type from those listed.
 - b) For JN5169 only: You will now be prompted to specify the maximum TX output power – select the Default TX Power mode (8.5 dBm) or one of the 3 other “fine steps” modes (“Default TX Power +0.8 dB” , “Default TX Power +1.2 dB” , “Default TX Power + 1.6 dB “) as appropriate.
 - c) You will now be prompted to specify if you want to use the internal 2.5 dB attenuator – select “Off” or “On” as appropriate.
 - d) For JN5169 only: You will now be prompted to specify the maximum RX input level – select 10dBm or 0 dBm as appropriate.
 - e) If you are using the main part of the tool, you will now be prompted to specify one of the following test modes:
 - TX Power Test (CW)
 - TX Power Test (Modulated)
 - Receive Test
 - Oscillator Frequency Test
 - Current Measurement Test
 - RF Power Measurement
 - Trigger Packet Test
 - Receive Packets Test
 - Transmit Packets Test
 - Connectionless Packet Error Rate Test
 - CCA Test
 - LQI

If you are using the PER tester, only one test mode is available.

The above test modes are described below.

Transmit Power Test (CW Mode)

The CW mode Transmit Power Test puts the device into a transmit state, generating a continuous wave signal.

Transmit Power Test (Modulated Mode)

The modulated Transmit Power Test mode puts the device into a transmit state, generating a signal modulated by a pseudo-random bit stream (PRBS). The duty cycle, power output level and operating frequency can be selected by the user.

Receive Test

The Receive Test mode puts the device in receive mode on a channel selected by the user, and generates a display showing the current received signal strength and peak signal strength in dBm, and Energy Detection (ED).

Oscillator Frequency Test

The Oscillator Frequency Test allows accurate measurements of the crystal oscillator frequency to be taken. When selected, the device is put into a test mode in which the 32-MHz microprocessor clock signal is output as a square wave on digital I/O pin DIO10.

Current Measurement Tests

This option offers a choice of the different modes that affect the device's electrical current consumption. Choosing one of these options allows current measurements to be taken in the corresponding mode.

The modes available are as follows:

- Microcontroller in deep sleep mode without memory retention
- Microcontroller in sleep mode without memory retention
- Microcontroller in sleep mode with memory retention
- Microcontroller in doze mode
- Microcontroller running
- Microcontroller running with protocol domain powered
- Microcontroller running with protocol domain powered and radio transmitting
- Microcontroller running with protocol domain powered and radio receiving

If carrying out sleep current measurements using a JN516x device on a DR1048 sensor board, the board current can be minimised by removing R9 to open circuit D9. Leakage current can also be minimised by setting the DIO control lines to the sensors HIGH and the DIO lines to D1 and D2 HIGH.



Caution: For the sleep mode current tests, depending on which serial terminal is being used, it may be necessary to disconnect the serial dongle and reset the board after the test is complete. This is due to some terminal emulators asserting the RTS signal, which is used by the JN51xx Flash Programmer to signal programming mode, causing the device to jump into programming mode upon start-up.

RF Power Measurement

When the RF Power Measurement option is selected, the JN516x device can be used as a simple RF power meter. This function continuously scans across channels and takes a measurement of the received energy on each channel. After a scan is complete, the highest recorded signal strength is displayed in dBm to an accuracy of about ± 3 dBm.

Trigger Packet Test

The Trigger Packet Test is designed to test the sensitivity of the receive path. In this mode, the device generates a trigger signal which should be connected to an arbitrary waveform generator configured to generate an ideal packet each time it is triggered. The number of trigger pulses generated, and hence the number of packets transmitted from the signal generator, can be configured by the user.

The external trigger input of the generator must be set in rising edge mode with an external delay equal to 2 ms.

The device counts the number of packets received, and displays the number of packets expected, the number of packets actually received, the number of chip errors detected, and the throughput of the system (as a percentage).

The DIO pin that carries the trigger signal can be selected by the user. By default, the DR1174 and DR1048 boards use DIO8 for this purpose.

Receive Packets Test

The Receive Packets Test puts the device into a mode that acts as a simple packet sniffer. In this test, the device is put into promiscuous mode, and will display the following information about each packet received:

- Timestamp, in microseconds, showing elapsed time since receiving the previous packet
- Packet type (e.g. Beacon, Data, Acknowledge, Mac Command, Reserved)
- Source address (short or extended)
- Destination address (short or extended)
- Sequence number
- ED (Energy Detection)
- SQI (Signal Quality Indicator)
- LQI (Link Quality Indicator)
- Packet checksum (good or bad)

Transmit Packets Test

The Transmit Packets Test transmits a packet at one of two rates – once every second (slow) or approximately once every 20 ms (fast). The packets are of type **data**, and are sent with the source extended address set to the MAC address of the module in use (displayed during the test), and a destination extended address of zero.

The packets have a 4-byte payload that is a 32-bit incrementing number equal to the “packets sent” value displayed during the test.

Connectionless Packet Error Rate Test

The Connectionless Packet Error Rate Test allows the measurement of packet error rate (PER) to be made using two modules running the Customer Module Evaluation Tool. One device must be configured as a slave, and the other device as a master that controls the test and displays the results. The test can be performed either with or without acknowledgments, on any selected channel. If using acknowledgments, the number of retries can be configured.

Clear Channel Assessment Test

The Clear Channel Assessment (CCA) test is used to obtain the result of a clear channel assessment. The different CCA modes and the threshold for CCA may each be selected.

CCA_MODE	Mode number
ENERGY_DETECT	1
CARRIER_DETECT	2
CARRIER_OR_ENERGY_DETECT	3
CARRIER_AND_ENERGY_DETECT	4

Link Quality Indicator (LQI)

The LQI Test mode puts the device in receive mode on a channel selected by the user, and generates a display showing the value of the current received signal LQI. The LQI value is in the range 0 to 255.

Packet Error Rate Test

The Packet Error Rate (PER) Test is designed to show real world performance of communications between two boards containing JN516x devices, and as such, this test requires two separate boards, each fitted with the same device type and each programmed with the **AN1172_ModulePerTest_JN51xx.bin** file.

The first board acts as the PER test master (the test controller) and the second as the PER test slave (the device under test).

Make the following connections between the two boards:

Master	Slave
DIO14 ←	→ DIO15
DIO15 ←	→ DIO14
GND ←	→ GND

On the DR1174 type boards (e.g. from the JN516x-EK001 evaluation kit), DIO14 is pin15 and DIO15 is pin16 on the expansion header.

These connections link UART 2 on the two boards to each other. This is required for test control purposes.

To start the test:

1. Connect the slave board to a PC with a USB cable or Serial cable (according to board type)
2. Establish a connection with Tera Term and choose "Run as PER test slave" from the Packet Error Rate Test menu.
3. Connect the master board to a PC with a USB cable or Serial cable (according to board type)
4. Establish a connection with Tera Term and choose "Run as PER test master" from the Packet Error Rate Test menu to begin the test.

Once the test has started, packets are transmitted from the master to the slave. The slave board keeps a count of the headers and whole packets received - if a whole packet is received successfully, the slave returns an acknowledge packet to the master. The master keeps a count of the acknowledgements received. 500 packets are sent on each channel and the results are displayed as percentages of successful packets (100% corresponds to all packets received).

Note: If two JN5169 SMA modules are used in the PER Test, the RF ports of the two modules should not normally be connected directly to each other. If they are directly connected, an attenuator must be placed between the modules with a minimum recommended attenuation of 3 dB.

Revision History

Version	Notes
1.0	First release
1.1	Software updated to support DR1215 LCD Expansion Board
1.2	Updated for BeyondStudio and Tera Term.
1.3	Updated for JN5169 device
1.4	Updated for JN5169 device April 2015
1.5	Updated with LQI test
1.6	New version because of JN5169 JPTLib change (CTrim=1 in radio init)

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